

ABSTRACT**OSCILLATING FIXED ABRASIVE CMP SYSTEM AND
METHODS FOR IMPLEMENTING THE SAME**

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A chemical mechanical polishing (CMP) apparatus (200) is provided. A first roller (212a) is situated at a first point and a second roller (212b) situated at a second point, such that the first point is separate from the second point. A polishing pad strip (202) is also included
10 and has a first end secured to the first roller and a second end secured to the second roller in a web handling arrangement. The polishing pad strip is configured to provide a surface onto which a substrate to be polished is lowered. Preferably, the polishing pad strip is a fixed abrasive pad and is configured to receive chemicals or DI water so as to facilitate a removal of material from a surface of the substrate.

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Figure 2A



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